

S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wing-Cheong Gilbert Lai et al.

Examiner: Unknown

Serial No.: Unknown

Group Art Unit: Unknown

Filed: Herewith

Docket: 303.261US3

Title: SMALL GRAIN SIZE, CONFORMAL ALUMINUM INTERCONNECTS AND
METHOD FOR THEIR FORMATION



INFORMATION DISCLOSURE STATEMENT

Box Patent Application
Commissioner for Patents
Washington, D.C. 20231

#3 | 155
7-10-01
R. H. H.

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for review in connection with the above-identified patent application. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner be returned to the Applicants.

In accordance with 37 C.F.R. §1.98(d), copies of the listed documents are not provided as these references were previously cited by or submitted to the U.S. Patent Office in connection with Applicants' prior U.S. application, Serial No. 09/146,509, filed on September 3, 1998, which is relied upon for an earlier filing date under 35 U.S.C. §120.

Applicants respectfully request consideration of these references during prosecution of the above-identified matter. The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

WING-CHEONG GILBERT LAI ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6976

Date 13 february 01 By Janal M. Kalis
Janal M. Kalis
Reg. No. 37,650

"Express Mail" mailing label number: EL671638680US

Date of Deposit: February 13, 2001

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to The Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

Form 1449*	Atty. Docket No.: 303.261US3	Serial No. Unknown
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Wing-Cheong Gilbert Lai et al. <i>09/782498</i>	
	Filing Date: Herewith <i>01/3/01</i>	Group: Unknown <i>2814</i>

U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>TU</i>	4,999,160	03/12/1991	Lowrey, T.A., et al.	420	529	12/04/89
	5,192,589	03/09/1993	Sandhu, G.S.	427	255.1	09/05/91
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FOREIGN PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No
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OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial	
<i>TU</i>	Fiordalice, R.W., et al., "Orientation Control of Chemical Vapor Deposition TiN Film for Barrier Applications", <u>Journal of the Electrochemical Society</u> , 143(6), pgs. 2059-2063, (June 1996)
	Lee, H., et al., "Study of Diffusion Barrier Performance in MOCVD TiN by Transmission Electron Microscopy", <u>Materials Research Society Symposium Proceedings</u> , 391, pgs. 205-209, (1995)
<i>TU</i>	Pramanik, D., et al., "Effect of Underlayer on Sputtered Aluminum Grain Structure and its Correlation with Step Coverage in Submicron Vias", <u>1990 Proceedings Seventh International IEEE VLSI Multilevel Interconnection Conference</u> , IEEE Catalog No. 90TH0325-1, pgs. 332 - 334, (June 1990)

Examiner <i>Quach</i>	Date Considered <i>11/15/02</i>
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*Substitute Disclosure Statement Form (PTO-1449)

**EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.